



SOT1898-1

plastic, thermal enhanced low profile quad flat package; 64 leads; 14 x 14 x 1.5 mm body; exposed die pad

1 September 2016

Package information

1. Package summary

Dimensions (mm)	14 x 14 x 1.5
Terminal position code	B
Package type descriptive code	HLQFP64
Package outline version code	SOT1898-1
Manufacturer package code	SOT1898
Package type industry code	HLQFP
Package outline version description	plastic, thermal enhanced low profile quad flat package; 64 leads; 14 x 14 x 1.5 mm body; exposed die pad
Package style descriptive code	HQFP
Package body material type	P
Mounting method type	S
Package life cycle status	REL
Security status	COMPANY PUBLIC
Issue date	1-9-2016
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	1.35	-	1.4	1.45	mm
A	seated height	-	-	-	1.6	mm
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	64	-	

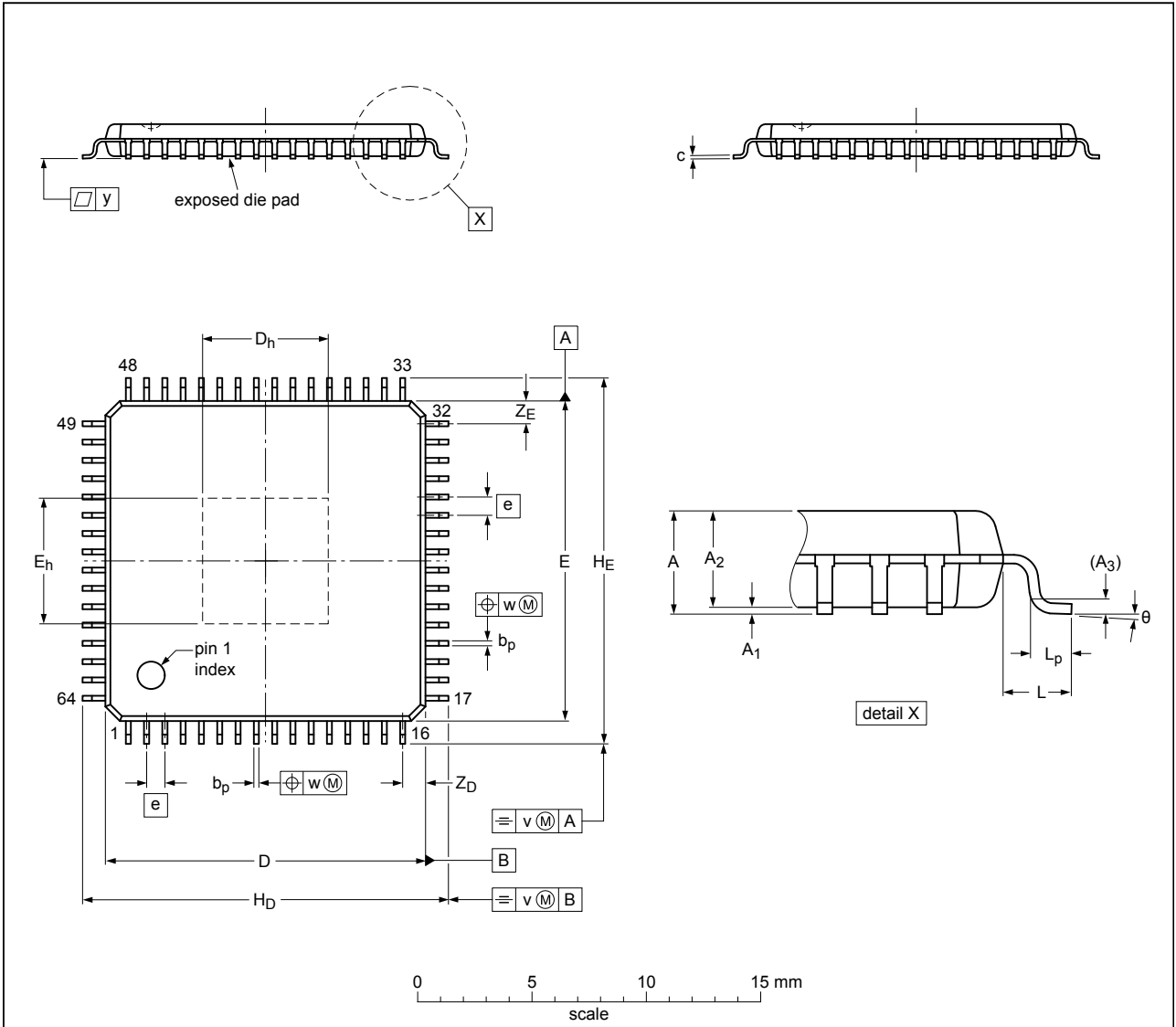


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2. Package outline

HLQFP64: plastic, thermal enhanced low profile quad flat package; 64 leads; 14 x 14 x 1.5 mm body; exposed die pad

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Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
max	1.6	0.15	1.45		0.26	0.20	14.1	5.6	14.1	5.6		16.15	16.15		0.75				1.15	1.15	7°
mm nom		0.10	1.40	0.25	0.22	0.15	14.0	5.5	14.0	5.5	0.8	16.00	16.00	1.0	0.60	0.2	0.08	0.08	1.00	1.00	
min		0.05	1.35		0.18	0.10	13.9	5.4	13.9	5.4		15.85	15.85		0.45				0.85	0.85	0°

Note

1. plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot1898-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1898-1		---			-16-08-30- 16-09-01

Fig. 1. Package outline HLQFP (SOT1898-1)

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3. Legal information

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